

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: Islam et al. Date: July 24, 2009
Application No.: 10/561,381 Examiner: F.F.Y. Lopez
Filing Date: December 16, 2005 Group Art Unit: 2826
Title: LEAD FRAME ROUTED CHIP PADS FOR
SEMICONDUCTOR PACKAGES

Mail Stop AF

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

AMENDMENT AFTER FINAL ACTION UNDER 37 C.F.R. § 1.116

Sir:

In response to the final Office Action mailed May 27, 2009, the Examiner is respectfully requested to amend the above-identified application as follows.

Amendments to the claims begin on page 2 of this paper.

Remarks begin on page 5 of this paper.

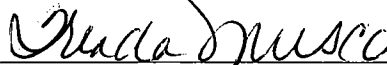
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I hereby certify that this correspondence (along with any paper referred to as being attached or enclosed) is being:

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July 24, 2009

Signed:


Brenda Musco